



# 100% Material Declaration Data Sheet BGG432

PK198 (v1.0.1) January 8, 2007

Material Declaration Data Sheet

**Average Weight: 8.7852 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.0585</b>	<b>0.67%</b>
	Silicon	7440-21-3	100.00		0.0585	
<b>Die Attach Material</b>					<b>0.007</b>	<b>0.07%</b>
	Resin	Trade Secret	25.00		0.002	
	Silver	7440-22-4	75.00		0.005	
<b>Mold Compound</b>					<b>0.3009</b>	<b>3.42%</b>
	Resin	Trade Secret	26.00		0.078	
	Silica	60676-86-0	74.00		0.233	
<b>Dam</b>					<b>0.0098</b>	<b>0.11%</b>
	Proprietary	Trade Secret	27.00		0.002646	
	Silica	60676-86-0	73.00		0.007154	
<b>Laminate</b>					<b>0.8377</b>	<b>9.54%</b>
	Copper	7440-50-8	15.51	Metal Layer	0.130	
	Nickel	7440-02-0	0.95	Metal Layer	0.008	
	Gold	7440-57-5	0.22	Metal Layer	0.002	
	Board	Trade Secret	61.24		0.513	
	Solder Mask (EP)	Trade Secret	22.08		0.185	
<b>Heat Sink</b>					<b>6.8302</b>	<b>77.75%</b>
	Copper	7440-50-8	100.00		6.8302	
<b>Heat Sink Plating</b>					<b>0.2920</b>	<b>3.32%</b>
	Nickel	7440-02-0	100.00		0.2920	
<b>Gold Wire</b>					<b>0.0191</b>	<b>0.22%</b>
	Gold	7440-57-5	100.00		0.0191	
<b>Solder Balls</b>					<b>0.430</b>	<b>4.90%</b>
	Tin	7440-31-5	95.50		0.411	
	Silver	7440-22-4	4.00		0.017	
	Copper	7440-50-8	0.50		0.002	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
10/5/06	1.0	Initial release.
1/8/07	1.0.1	Corrected Gold Wire CAS# entry.